

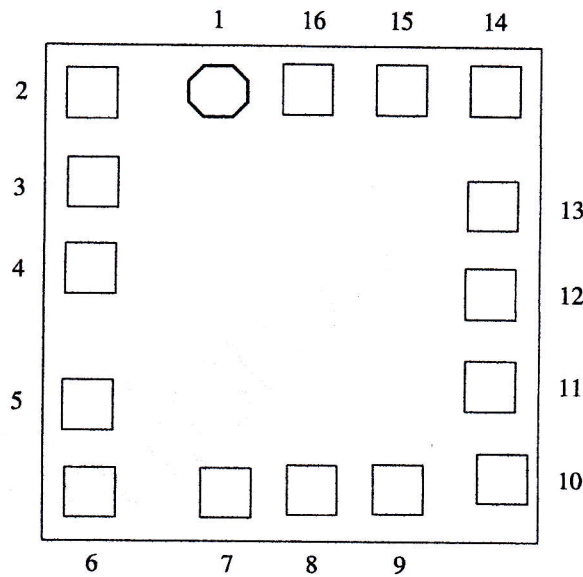


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PAD FUNCTIONS



1. V_{CC1}
2. N.Aout
3. N.Bout
4. Ain
5. Aout
6. Bout
7. Bin
8. V_{EE}
9. Dout
10. Cin
11. Cout
12. Common Input
13. Din
14. N.Cout
15. N.D.out
16. V_{CC2}

The information given is believed to be correct at the time of issue.

Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.

Back potential is the electrical potential of the substrate (bulk silicon), which may not require an electrical connection unless stated in this drawing.

Note: 1 mil = 0.001inch

<u>APPROVED</u> GB DATE: 19/03/13	<h2>MC10H101</h2> <h3>ON SEMICONDUCTOR</h3>	<u>DIE INFORMATION</u> DIMENSIONS (Mils): 38 x 40 BOND PADS (Mils): MASK REF: GEOMETRY: BACK POTENTIAL:
DG 10.1.2 Rev B, 7/19/02		<u>METALLISATION</u> TOP: Al BACK: Si